



### PATENT APPLICATION

Group Art Unit: NOT YET ASSIGNED

Examiner: NOT YET ASSIGNED

## RYTHE WNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Mitsuo OSADA, et al.

Appln. No.: 10/009,822

Confirmation No.:6202

Filed: December 13, 2001

For: MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A

SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC

PACKAGE USING THE SAME

# REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Commissioner for Patents
Office of Initial Patent Examination
Customer Service Center
Washington, D.C. 20231

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**Technology Center 2600** 

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and request the following correction:

Foreign Applications: Please delete "JAPAN 17584/2000 01/26/2000 because it does not claim foreign priority.

Verification for the requested correction is indicated on the original Declaration and Power of Attorney filed December 13, 2001.

Respectfully submitted,

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Date: May 10, 2002

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APPLICATION NUMBER | FILING DATE | GRP ART UNIT | FIL FEE REC'D | ATTY.DOCKET.NO | DRAWINGS | TOT CLAIMS | IND CLAIMS | 10/009.822 | 12/13/2001 | 2835 | 974 | Q67726 | 3 | 14 | 4 |

**CONFIRMATION NO. 6202** 

23373 SUGHRUE MION, PLLC 2100 PENNSYLVANIA AVENUE, N.W. WASHINGTON, DC 20037 FILING RECEIPT

\*OC000000007425594\*

Date Mailed: 02/07/2002

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP01/03164 04/12/2001

Foreign Applications

JAPAN 17504/2000 01/26/2000 PRIORITY

JAPAN 372405/2000 12/07/2000

Projected Publication Date: To Be Determined - pending completion of Security Review

Non-Publication Request: No

Early Publication Request: No

Title

م الما مع دين.

Material of heat-dissipating plate on which semiconductor is mounted, method for fabricating the same, and ceramic package produced by using the same

**Preliminary Class** 

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